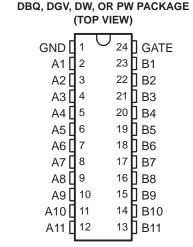
- Designed to be Used in Voltage-Limiting Applications
- 6.5-Ω On-State Connection Between Ports A and B
- Flow-Through Pinout for Ease of Printed Circuit Board Trace Routing
- Direct Interface With GTL+ Levels
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 1000-V Charged-Device Model (C101)

#### description/ordering information

The SN74TVC3010 provides 11 parallel NMOS pass transistors with a common gate. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.



The device can be used as a 10-bit switch with the gates cascaded together to a reference transistor. The low-voltage side of each pass transistor is limited to a voltage set by the reference transistor. This is done to protect components with inputs that are sensitive to high-state voltage-level overshoots. (See Application Information in this data sheet.)

All of the transistors in the TVC array have the same electrical characteristics; therefore, any one of them can be used as the reference transistor. Since, within the device, the characteristics from transistor to transistor are equal, the maximum output high-state voltage ( $V_{OH}$ ) is approximately the reference voltage ( $V_{REF}$ ), with minimal deviation from one output to another. This is a large benefit of the TVC solution over discrete devices. Because the fabrication of the transistors is symmetrical, either port connection of each bit can be used as the low-voltage side, and the I/O signals are bidirectional through each FET.

#### ORDERING INFORMATION

TA	PACKAGE	<u></u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC - DW	Tube	SN74TVC3010DW	TVC3010
	301C - DW	Tape and reel	SN74TVC3010DWR	1 0 0 3 0 1 0
–40°C to 85°C	SSOP (QSOP) – DBQ	Tape and reel	SN74TVC3010DBQR	TVC3010
	TSSOP – PW	Tape and reel	SN74TVC3010PWR	TT010
	TVSOP – DGV	Tape and reel	SN74TVC3010DGVR	TT010

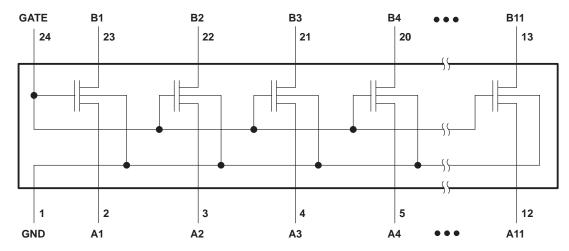
<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



# simplified schematic



# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

, , ,	0.5 V to 7 V 0.5 V to 7 V
	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): D	BQ package 61°C/W
D	GV package 86°C/W
D	W package 46°C/W
P	W package 88°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

		MIN	TYP	MAX	UNIT
V <sub>I/O</sub>	Input/output voltage	0		5	V
VGATE	GATE voltage	0		5	V
IPASS	Pass-transistor current		20	64	mA
TA	Operating free-air temperature	-40		85	°C



NOTES: 1. The input and input/output negative-voltage ratings may be exceeded if the input and input/output clamp-current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

# application operating conditions (see Figure 3)

		MIN	TYP	MAX	UNIT
VBIAS	BIAS voltage	V <sub>REF</sub> + 0.6	2.1	5	V
VGATE	GATE voltage	V <sub>REF</sub> + 0.6	2.1	5	V
VREF	Reference voltage	0	1.5	4.4	V
V <sub>DPU</sub>	Drain pullup voltage	2.36	2.5	2.64	V
IPASS	Pass-transistor current		14		mA
IREF	Reference-transistor current		5		μΑ
TA	Operating free-air temperature	-40		85	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	3	MIN	TYP <sup>†</sup>	MAX	UNIT
VIK	$V_{BIAS} = 0$ ,	$I_{I} = -18 \text{ mA}$				-1.2	V
V <sub>OL</sub>	I <sub>REF</sub> = 5 μA, V <sub>DPU</sub> = 2.625 V,	$V_{REF} = 1.365 \text{ V},$ $R_{DPU} = 150 \Omega$	$V_S = 0.175 \text{ V},$ See Figure 1			350	mV
C <sub>i(GATE)</sub>	V <sub>I</sub> = 3 V or 0				24		pF
C <sub>io(off)</sub>	V <sub>O</sub> = 3 V or 0				4	12	pF
C <sub>io(on)</sub>	V <sub>O</sub> = 3 V or 0				12	30	pF
r <sub>on</sub> ‡	I <sub>REF</sub> = 5 μA, V <sub>DPU</sub> = 2.625 V,	$V_{REF} = 1.365 V$ , $R_{DPU} = 150 \Omega$	$V_S = 0.175 V$ , See Figure 1			12.5	Ω

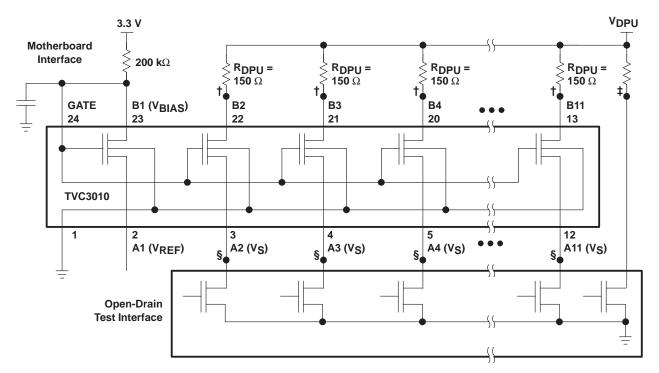
<sup>&</sup>lt;sup>†</sup> All typical values are at  $T_A = 25$ °C.

# switching characteristics over recommended operating free-air temperature range, $V_{DPU} = 2.36 \text{ V}$ to 2.64 V (unless otherwise noted) (see Figure 1)

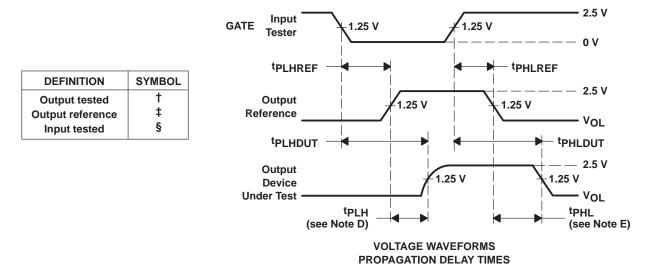
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
tPLH	A or B	B or A	0	4	20
t <sub>PHL</sub>	AUB	BULA	0	4	ns

<sup>&</sup>lt;sup>‡</sup> Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

#### PARAMETER MEASUREMENT INFORMATION



TESTER CALIBRATION SETUP (see Note C)



NOTES: A. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f \leq 2 \ ns$ .

- B. The outputs are measured one at a time with one transition per measurement.
- C. Test procedure: tpLHREF and tpHLREF are obtained by measuring the propagation delay of a reference measuring point. tPLHDUT and tPHLDUT are obtained by measuring the propagation delay of the device under test.
- D. tplH = tplHDUT tplHREF E. tpHL = tpHLDUT tpHLREF

Figure 1. Tester Calibration Setup and Voltage Waveforms



#### TVC background information

In personal computer (PC) architecture, there are industry-accepted bus standards. These standards define, among other things, the I/O voltage levels at which the bus communicates. Examples include the GTL+ host bus, the AGP graphics port, and the PCI local bus. In new designs, the system components must communicate with existing bus infrastructure. Providing an evolutionary upgrade path is important in the design of PC architecture, but the existing bus standards must be preserved.

To achieve the ever-present need for smaller, faster, lighter devices that draw less power, yet have faster performance, most new high-performance digital integrated circuits are being designed and produced with advanced submicron semiconductor process technologies. These devices have thin gate-oxide or short channel lengths and very low absolute-maximum voltages that can be tolerated at the inputs/outputs (I/Os) without causing damage. In many cases, the I/Os of these devices are not tolerant of the high-state voltage levels on the preexisting buses with which they must communicate. Therefore, it became necessary to protect the I/Os of devices by limiting the I/O voltages.

The Texas Instruments (TI) translation voltage-clamp (TVC) family was designed specifically for protecting sensitive I/Os (see Figure 2). The information in this data sheet describes the I/O-protection application of the TVC family and should enable the design engineer to successfully implement an I/O-protection circuit utilizing the TI TVC solution.

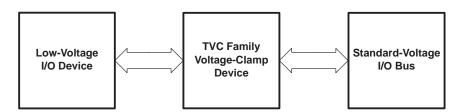
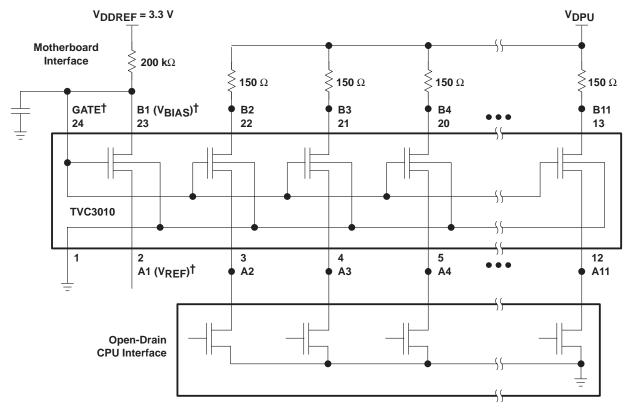


Figure 2. Thin Gate-Oxide Protection Application

#### TVC voltage-limiting application

For the voltage-limiting configuration, the common GATE input must be connected to one side (A or B) of any one of the transistors (see Figure 3). This connection determines the  $V_{BIAS}$  input of the reference transistor. The  $V_{BIAS}$  input is connected through a pullup resistor (typically,  $200\,\mathrm{k}\Omega$ ) to the  $V_{DD}$  supply. A filter capacitor on  $V_{BIAS}$  is recommended. The opposite side of the reference transistor is used as the reference voltage ( $V_{REF}$ ) connection. The  $V_{REF}$  input must be less than  $V_{DDREF}-1$  V to bias the reference transistor into conduction. The reference transistor regulates the gate voltage ( $V_{GATE}$ ) of all the pass transistors.  $V_{GATE}$  is determined by the characteristic gate-to-source voltage difference ( $V_{GS}$ ) because  $V_{GATE}=V_{REF}+V_{GS}$ . The low-voltage side of the pass transistors has a high-level voltage limited to a maximum of  $V_{GATE}-V_{GS}$ , or  $V_{REF}$ .



<sup>†</sup> VREF and VBIAS can be applied to any one of the pass transistors. GATE must be connected externally to VBIAS.

Figure 3. Typical Application Circuit



#### electrical characteristics

The electrical characteristics of the NMOS transistors used in the TVC devices are illustrated by TI SPICE simulations. Figure 4 shows the test configuration for the TI SPICE simulations. The results, shown in Figures 5 and 6, show the current through a pass transistor versus the voltage at the source for different reference voltages. The plots of the dc characteristics clearly reveal that the device clamps at the desired reference voltage for the varying device environments.

Figure 5 shows the V-I characteristics, with low reference voltages and a reference-transistor drain-supply voltage of 3.3 V. To further investigate the spread of the V-I characteristic curves,  $V_{REF}$  was held at 2.5 V and  $I_{REF}$  was increased by raising  $V_{DDRFF}$  (see Figure 6). The result was a tighter grouping of the V-I curves.

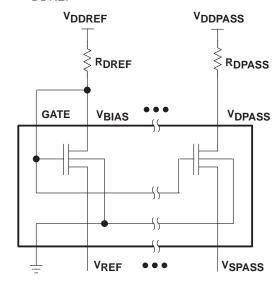


Figure 4. TI SPICE Simulation Schematic and Voltage-Node Names

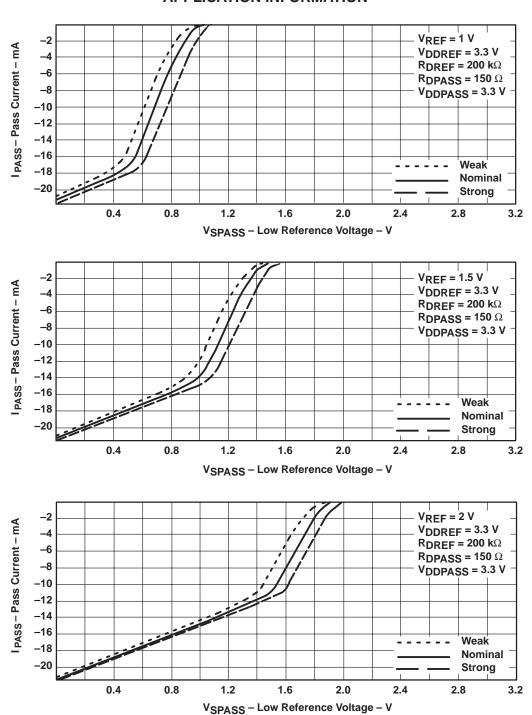


Figure 5. Electrical Characteristics at Low V<sub>REF</sub> Voltages



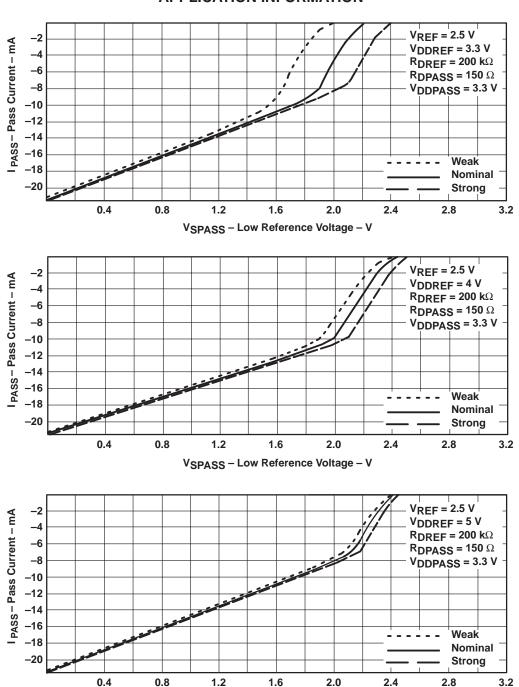


Figure 6. Electrical Characteristics at V<sub>REF</sub> = 2.5 V

VSPASS - Low Reference Voltage - V



#### features and benefits

The TVC family has several features that benefit a system designer when implementing a sensitive-I/O-protection solution. Table 1 lists these features and their associated benefits.

Table 1. Features and Benefits

FEATURES	BENEFITS
Any FET can be used as the reference transistor.	Ease of layout
All FETs on one die, tight process control	Very low spread of VO relative to VREF
No active control logic (passive device)	No logic power supply (V <sub>CC</sub> ) required
Flow-through pinout	Ease of trace routing
Devices offered in different bit-widths and packages	Optimizes design and cost effectiveness
Designer flexibility with V <sub>REF</sub> input	Allows migration to lower-voltage I/Os without board redesign

#### conclusion

The TI TVC family provides the designer with a solution for protection of circuits with I/Os that are sensitive to high-state voltage-level overshoots. The flexibility of TVC enables a low-voltage migration path for advanced designs to align with industry standards.

### frequently asked questions (FAQ)

- 1. Q: Can any of the transistors in the array be used as the reference transistor?
  - A: Yes, any transistor can be used as long as its V<sub>BIAS</sub> pin is connected to the GATE pin.
- Q: In the recommended operating conditions table of the data sheet, the typical V<sub>BIAS</sub> is 3.3 V. Should V<sub>BIAS</sub> be equal to or greater than V<sub>REF</sub> on the reference transistor?
  - A: V<sub>BIAS</sub> is a variable that is determined by V<sub>REF</sub>. V<sub>BIAS</sub> is connected to V<sub>DD</sub> through a resistor to allow the bias voltage to be controlled by V<sub>REF</sub>. V<sub>DD</sub> can be as high as 5.5 V. V<sub>REF</sub> needs to be at least 1 V less than V<sub>DDRFF</sub> on the reference transistor.
- 3. Q: Do both A and B ports have 5-V I/O tolerance or is 5-V I/O tolerance provided only on the low-voltage side?
  - A: Both ports are 5-V tolerant.









#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74TVC3010DBQR	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74TVC3010DBQRE4	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74TVC3010DBQRG4	ACTIVE	SSOP/ QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74TVC3010DGVR	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010DGVRE4	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010DGVRG4	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010PW	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010PWE4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010PWG4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010PWR	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010PWRE4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74TVC3010PWRG4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



### PACKAGE OPTION ADDENDUM

24-May-2007

package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

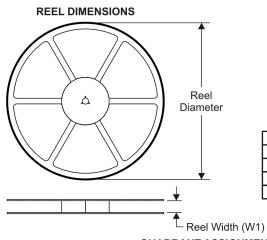
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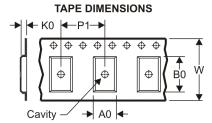
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# PACKAGE MATERIALS INFORMATION

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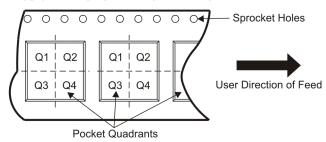
# TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

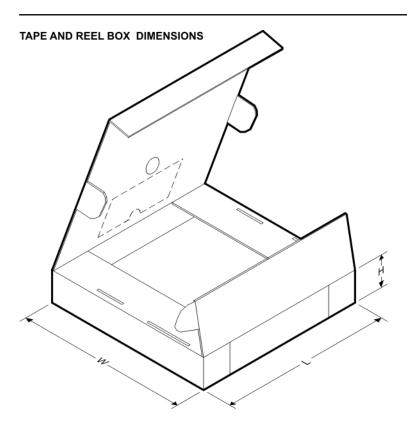
# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All difference are from that												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74TVC3010DBQR	SSOP/ QSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74TVC3010DGVR	TVSOP	DGV	24	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74TVC3010DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74TVC3010PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74TVC3010DBQR	SSOP/QSOP	DBQ	24	2500	346.0	346.0	33.0
SN74TVC3010DGVR	TVSOP	DGV	24	2000	346.0	346.0	29.0
SN74TVC3010DWR	SOIC	DW	24	2000	346.0	346.0	41.0
SN74TVC3010PWR	TSSOP	PW	24	2000	346.0	346.0	33.0

# DGV (R-PDSO-G\*\*)

### 24 PINS SHOWN

#### **PLASTIC SMALL-OUTLINE**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194 DW (R-PDSO-G24)

# PLASTIC SMALL OUTLINE



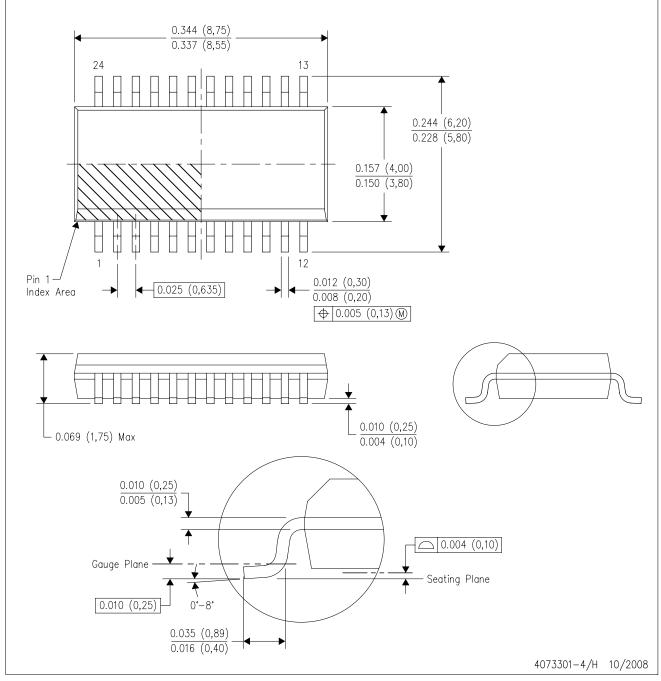
NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DBQ (R-PDSO-G24)

# PLASTIC SMALL-OUTLINE PACKAGE

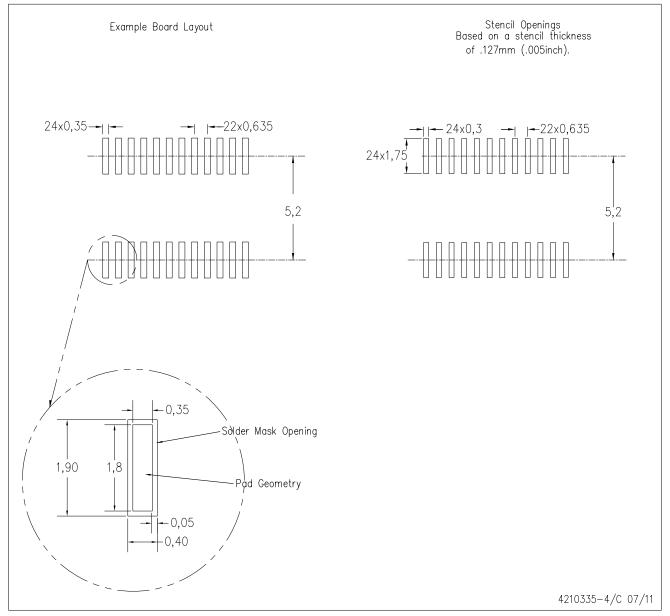


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
- D. Falls within JEDEC MO-137 variation AE.



DBQ (R-PDSO-G24)

# PLASTIC SMALL OUTLINE PACKAGE

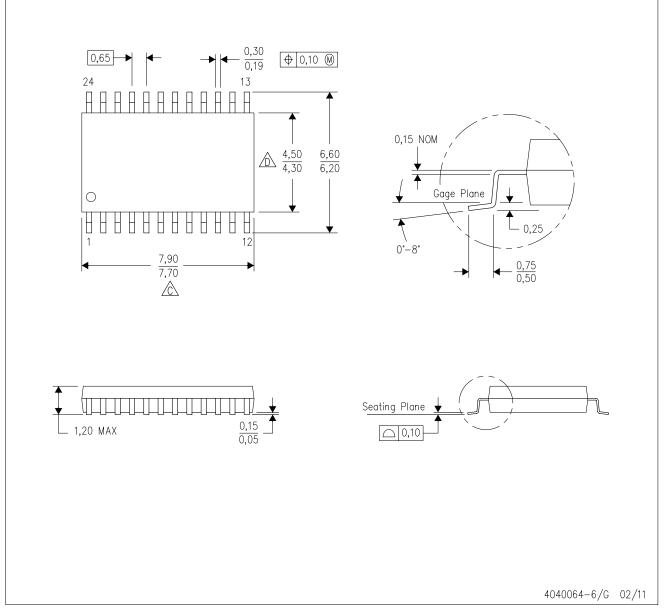


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



PW (R-PDSO-G24)

# PLASTIC SMALL OUTLINE

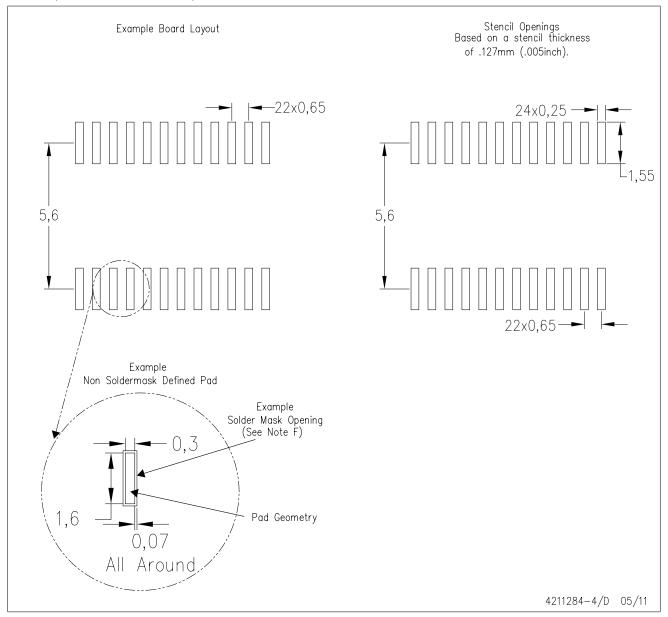


- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



# PW (R-PDSO-G24)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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